

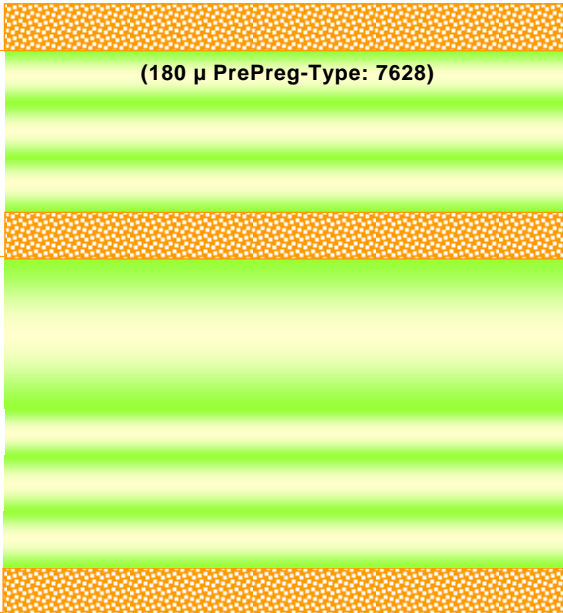
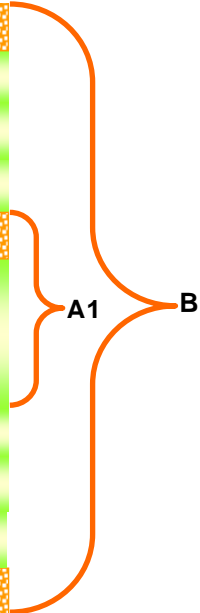
**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
---	---	---	---	---	---	-----------

03	168	FR4	55	L46.35	P18	S1
----	-----	-----	----	--------	-----	----

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**03\_168\_FR4\_55\_L46.35\_p18\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly
<b>Layer-1</b>	55 $\mu$	Copper		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
<b>Layer-2</b>	35 $\mu$	Copper		
	460 $\mu$	L-FR4		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
<b>Layer-99</b>	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	35 $\mu$	Copper		

© Copyright by Printed Circuit Boards GmbH